

WI-FI Module (EMW3080-BP)

MB1400

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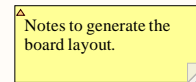
Sheet 1 : Project Overview
Sheet 2 : Emw3080_Module

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



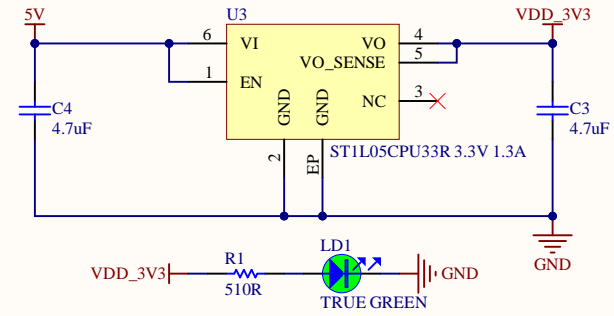
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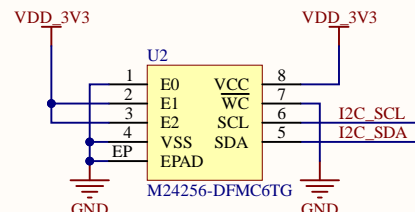
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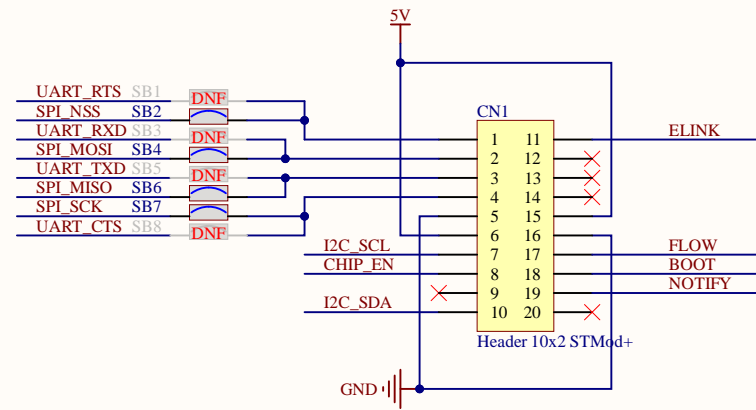
POWER



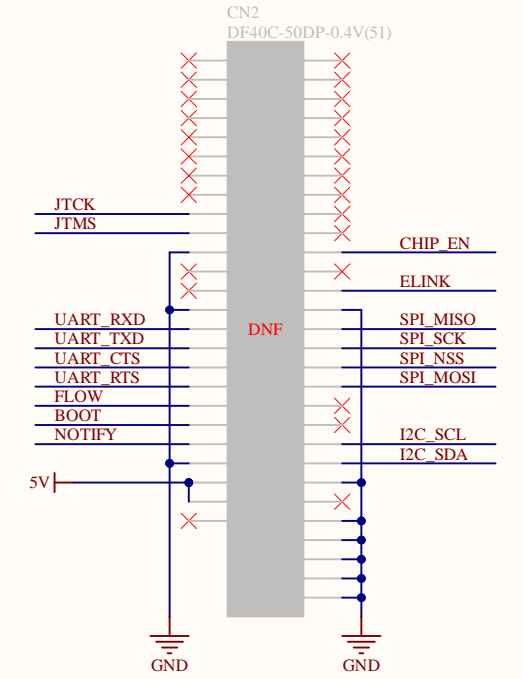
I2C Bus EEPROM



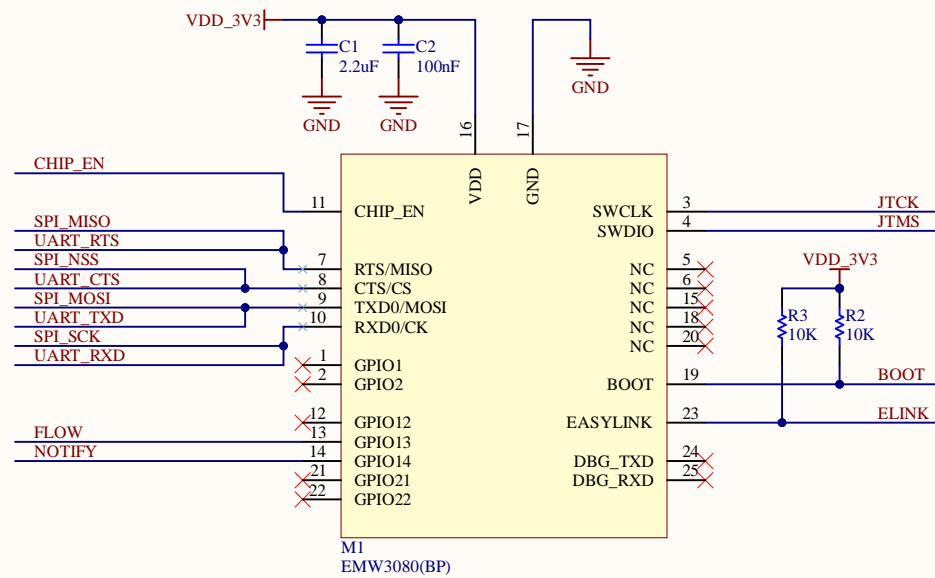
STMOD+ connector



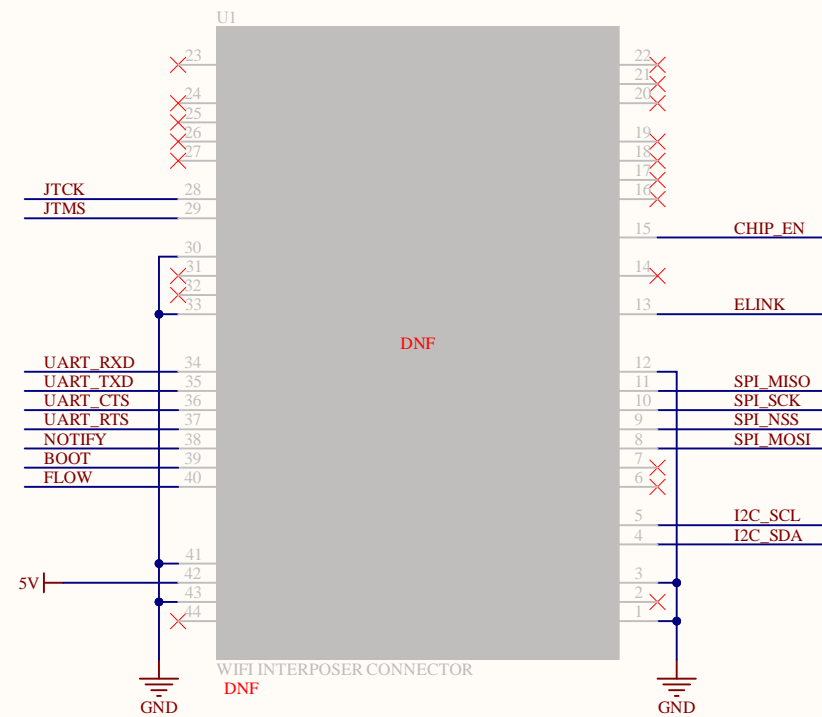
DF40C connector



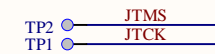
WI-FI MODULE (EMW3080BP)



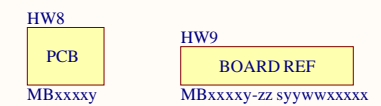
INTERPOSER CONNECTOR

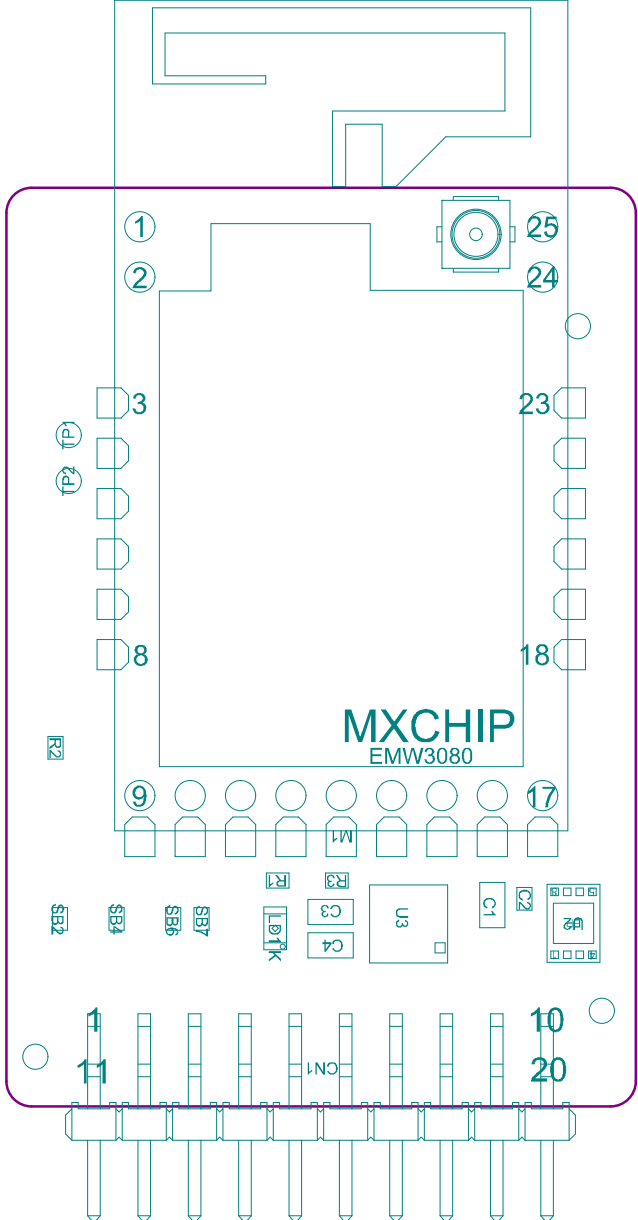


DEBUG



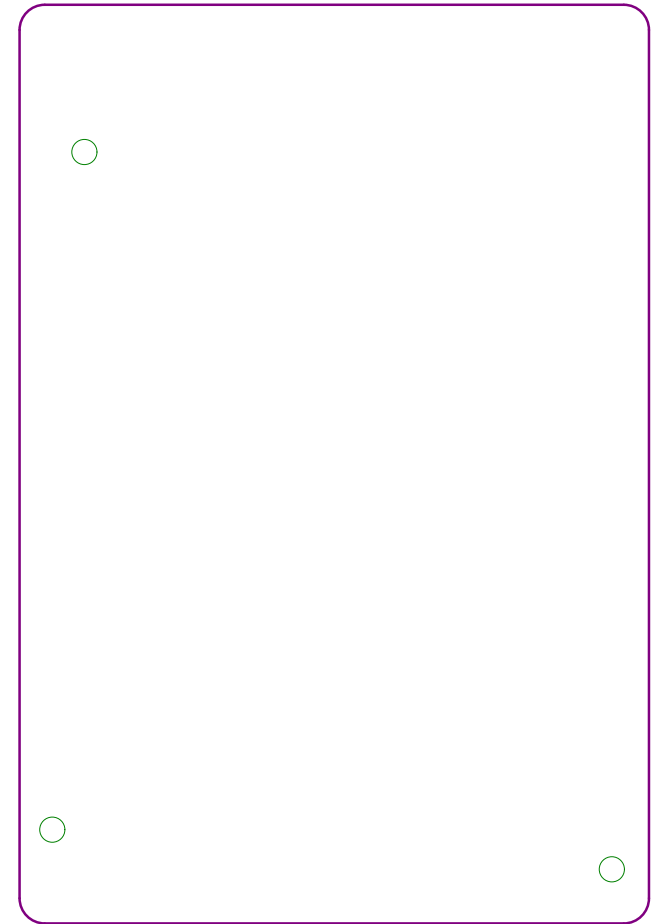
PCB & sticker




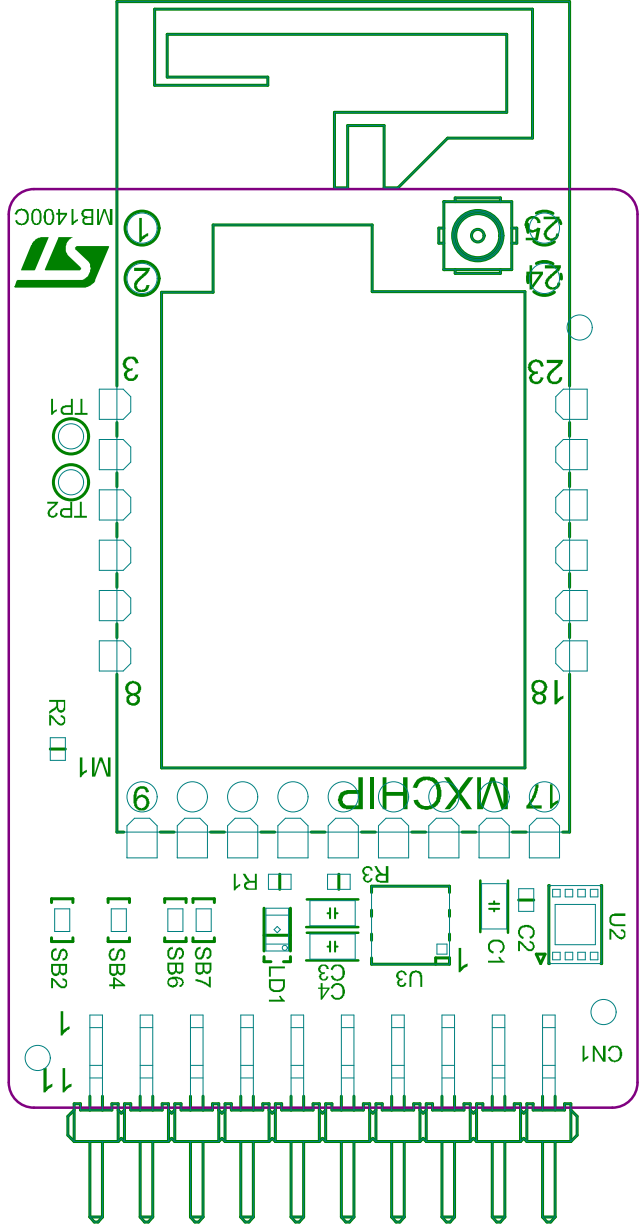


Project: WI-FI Module (EMW3080-BP)	
Layer: M14-Top Assembly	Gerber: .GM14
Variant: STMod+_SPI	Ref: MB1400
Date: 6-APR-2020	Rev: C



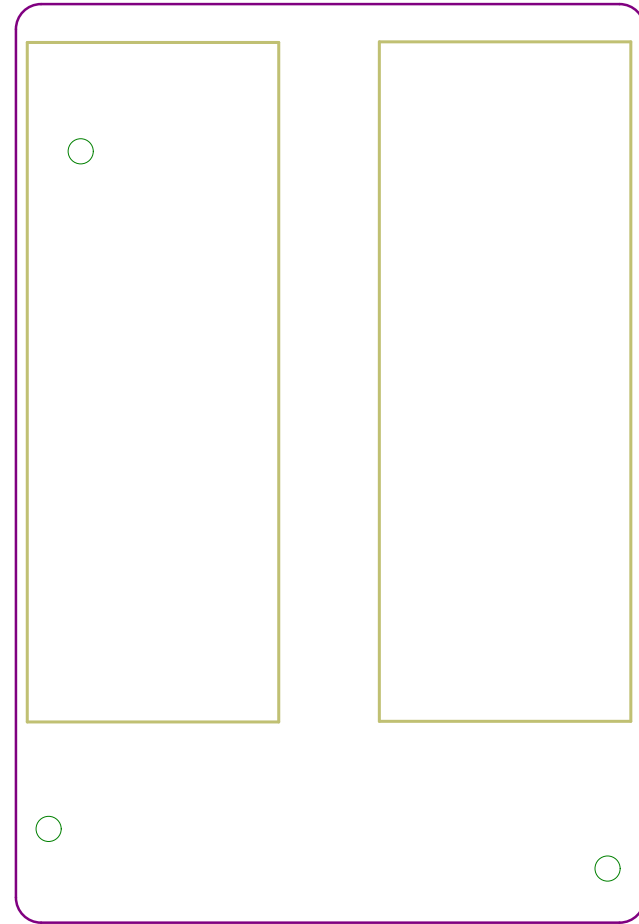


Project: WI-FI Module (EMW3080-BP)		
Layer: M15-Bottom Assembly	Gerber: .GM15	
Variant: STMod+_SPI	Ref: MB1400	
Date: 6-APR-2020	Rev: C	



Mdp4-Overlay Assembly

.G104



M15-Bottom Assembly
Bottom Overlay

.GM15